

Performance

- Frequency: DC~8GHz
- Mounting: Wire bonding
- Attenuation: 3,4,5,6dB
- Temperature Compensate (dB/dB/°C)
0.007, 0.008, 0.009
- Rated Power: 200mW
- Chip size: 1.91*1.52*0.3mm

Naming Rule

BTVA 03 N 07 G A

① ② ③ ④ ⑤ ⑥

① Series Name

② Attenuation: 03=3dB,04=4dB,05=5dB,06=6dB

③ N= Negative Temperature characteristic

④ Temp Compensate Figure (dB/dB/°C)

07=0.007, 08=0.008, 09=0.009

⑤ Mounting: G=Wire Bonding

⑥ Outline size and pad information

Electrical Specifications (Ta=+25°C, 50Ω system)

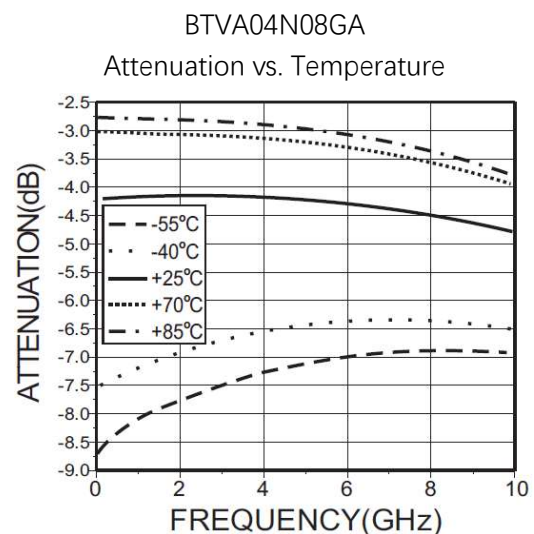
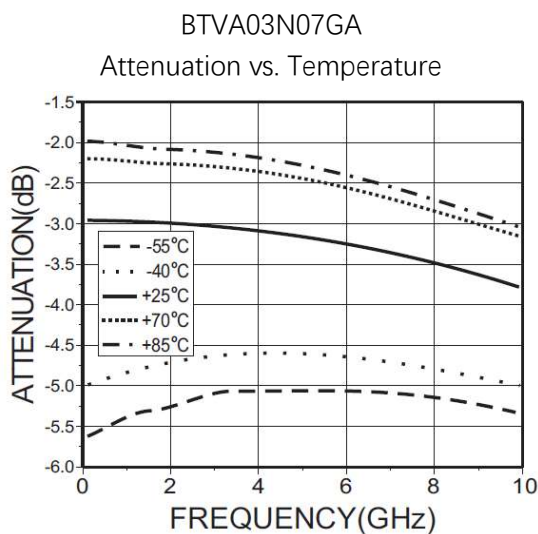
Part Number	Attenuation (dB)	Return Loss (dB)	Attenuation Flatness (dB)	Return Loss (dB)	Attenuation Flatness (dB)
		DC~3GHz		3~8GHz	
BTVA03N07GA	3	-16	±0.5	-12	±0.8
BTVA04N08GA	4	-16	±0.5	-12	±0.8
BTVA05N09GA	5	-16	±0.5	-12	±0.8
BTVA06N07GA	6	-16	±0.5	-12	±0.8

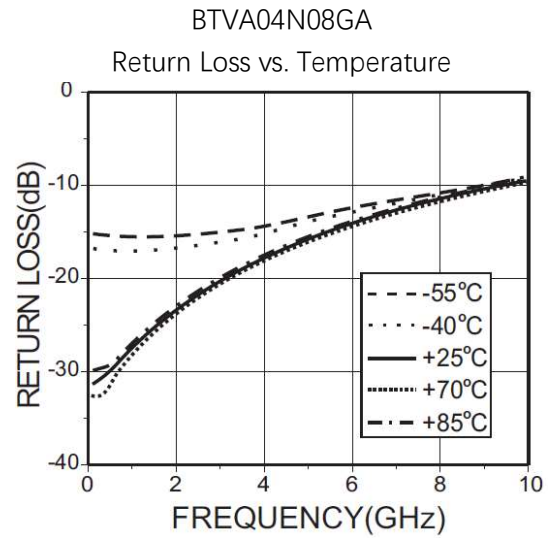
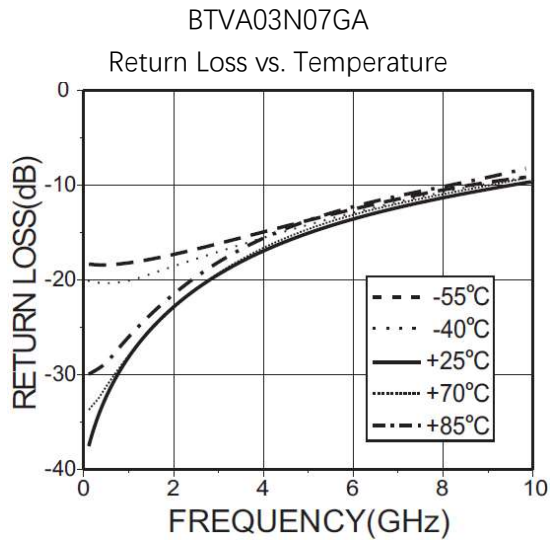
Absolute Max Ratings

Rated Power (CW)	200mW
Power Derating	100% @ +125°C, 0% @ +150°C
Operating Temperature	-55°C~+85°C

Note: For high power application, please ensure the good heating sinking condition.

Test Curves





Outline Size (A type) mm	Mounting Method (Wire bonding)
Dimensions (mm): Top width: 0.64 Top right width: 0.46 Bottom width: 1.91 ± 0.15 Height: 1.52 ± 0.15 Bottom right width: 0.25 Tolerance (公差): 0.3	Wire bonding details: 2根1 MIL 金线或1根10 MIL 金带 RF I/O 3 MIL 装配间距 GND 50ohm 传输线